

## N and P-Channel Enhancement Mode Power MOSFET

### Description

The HMI<sup>™</sup> EO uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

### General Features

- N-Channel

$V_{DS} = 10V, I_D = 1A$

$R_{DS(ON)} < 41m\Omega @ V_{GS}=4.5V$

$R_{DS(ON)} < 68m\Omega @ V_{GS}=2.5V$

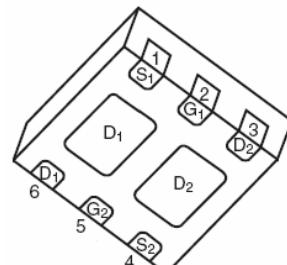
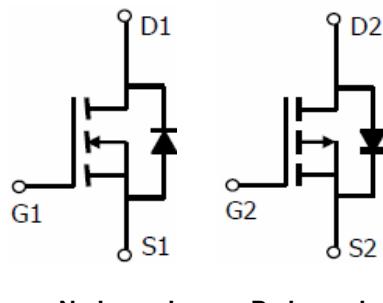
- P-Channel

$V_{DS} = -10V, I_D = -1A$

$R_{DS(ON)} < 80m\Omega @ V_{GS}=-4.5V$

$R_{DS(ON)} < 135m\Omega @ V_{GS}=-2.5V$

- High power and current handing capability
- Lead free product is acquired
- Surface mount package



Pin assignment

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
20**	HMI <sup>™</sup> EO	ÖÖP GY GT S	Ø180mm	MM{ {	3000 units

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	$V_{DS}$	10	-10	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	$\pm 12$	V
Continuous Drain Current  $T_A=25^\circ C$	$I_D$	1	-1	A
		H1	-H1	
Pulsed Drain Current <sup>(Note 1)</sup>	$I_{DM}$	1I	-1I	A
Maximum Power Dissipation	$P_D$	0.8	0.8	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance,Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	N-Ch	156	°C/W
Thermal Resistance,Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	P-Ch	156	°C/W

**N-CH Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	22	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	F. € 1.5V	F. € 1.5V	F. € 1.5V	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=2.8\text{A}$	-	33	41	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=1\text{A}$	-	46	68	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=1\text{A}$	-	8	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	260	-	PF
Output Capacitance	$C_{\text{oss}}$		-	48	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	27	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=10\text{V}, R_{\text{L}}=3.3\Omega$ $V_{\text{GS}}=4.5\text{V}, R_{\text{GEN}}=6\Omega$	-	2.5	-	nS
Turn-on Rise Time	$t_r$		-	3.2	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	21	-	nS
Turn-Off Fall Time	$t_f$		-	3	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=1\text{A}, V_{\text{GS}}=4.5\text{V}$	-	2.9	5	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	0.4	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	0.6	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A}$	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_{\text{S}}$		-	-	5	A

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

**P-CH Electrical Characteristics (TA=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-40		-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-40V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-2.0	-3.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-2.5A$	-	72	80	$m\Omega$
		$V_{GS}=-2.5V, I_D=-2A$	-	110	135	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-5V, I_D=-2.5A$	-	9.5	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	$C_{iss}$	$V_{DS}=-10V, V_{GS}=0V, F=1.0MHz$	-	325	-	PF
Output Capacitance	$C_{oss}$		-	63	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	37	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-10V, R_L=5\Omega, V_{GS}=-4.5V, R_{GEN}=3\Omega$	-	11	-	nS
Turn-on Rise Time	$t_r$		-	5.5	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	22	-	nS
Turn-Off Fall Time	$t_f$		-	8	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-10V, I_D=-2A, V_{GS}=-4.5V$	-	3.2	-	nC
Gate-Source Charge	$Q_{gs}$		-	0.6	-	nC
Gate-Drain Charge	$Q_{gd}$		-	0.9	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=-5A$	-	-	-1.2	V
Diode Forward Current (Note 2)	$I_S$		-	-	-5	A

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

### N- Channel Typical Electrical and Thermal Characteristics (Curves)

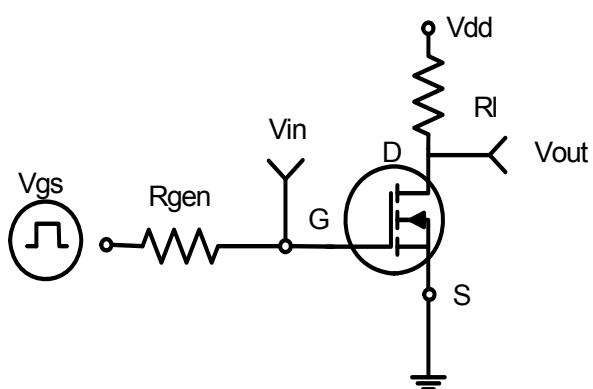


Figure 1:Switching Test Circuit

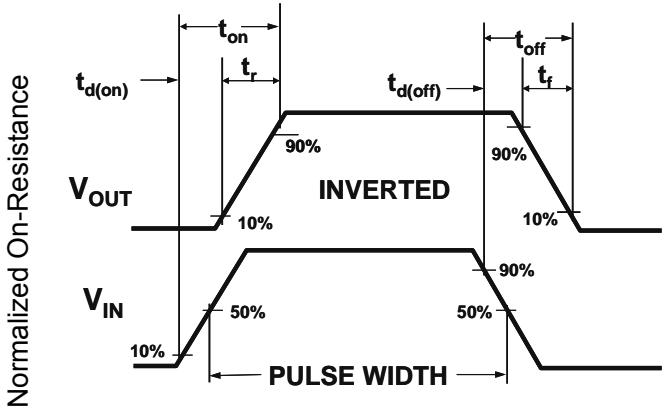


Figure 2:Switching Waveforms

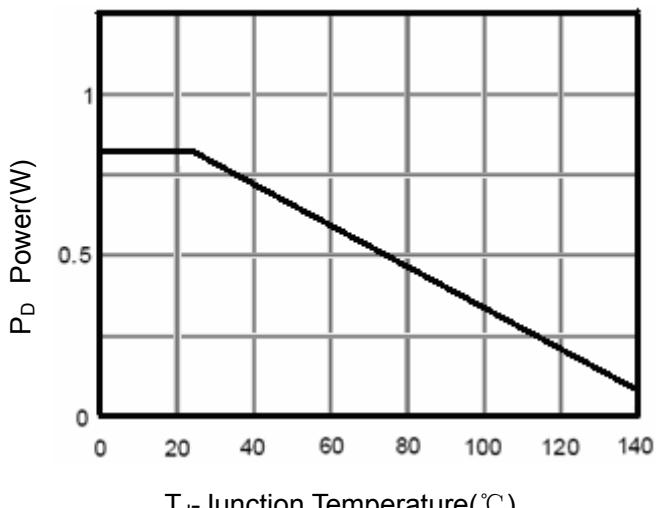


Figure 3 Power Dissipation

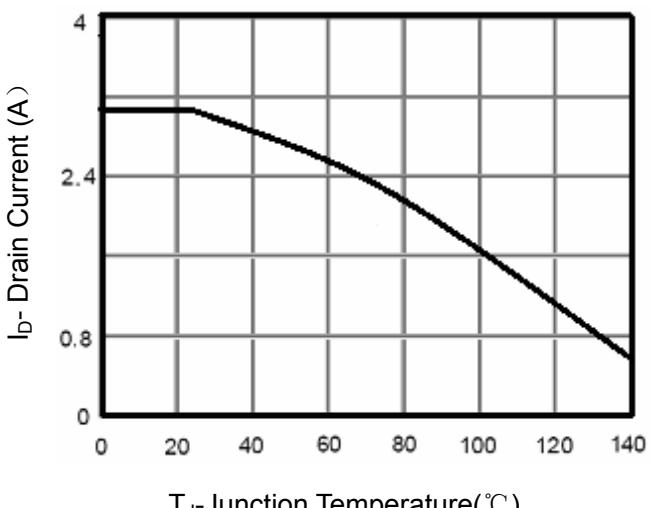


Figure 4 Drain Current

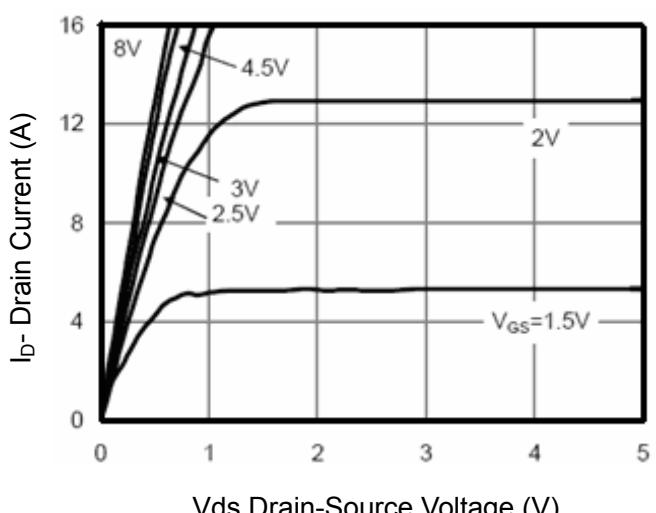


Figure 5 Output Characteristics

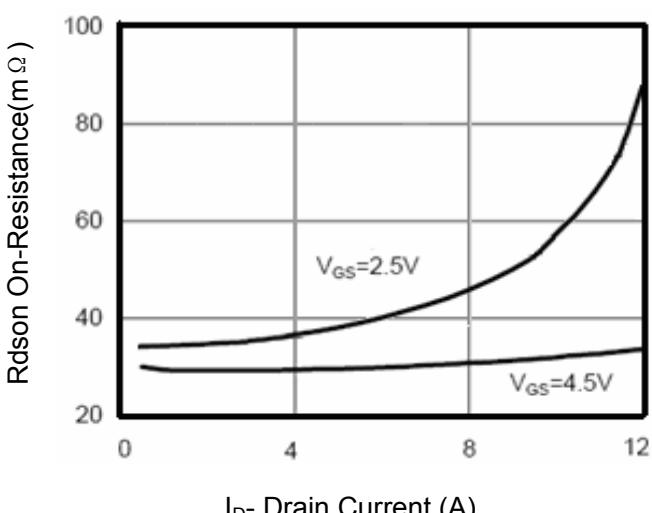
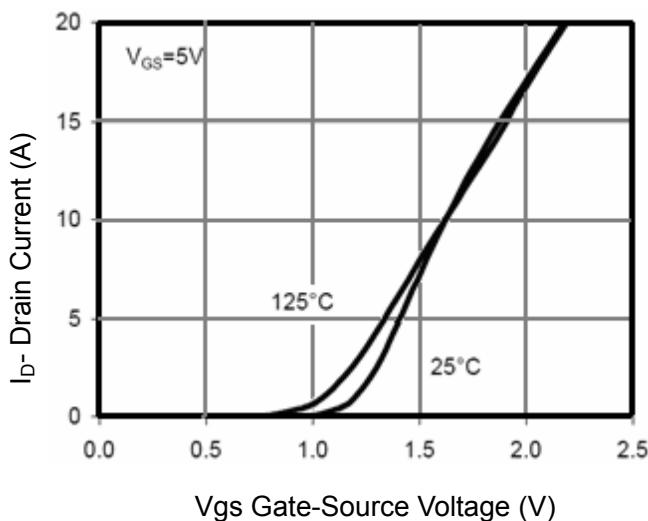
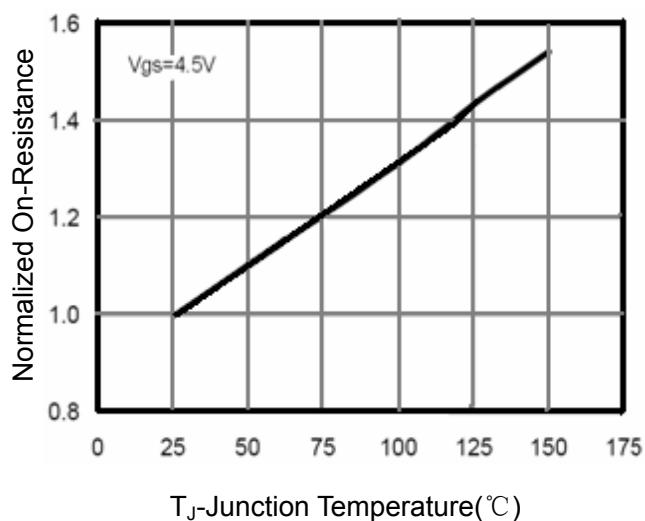


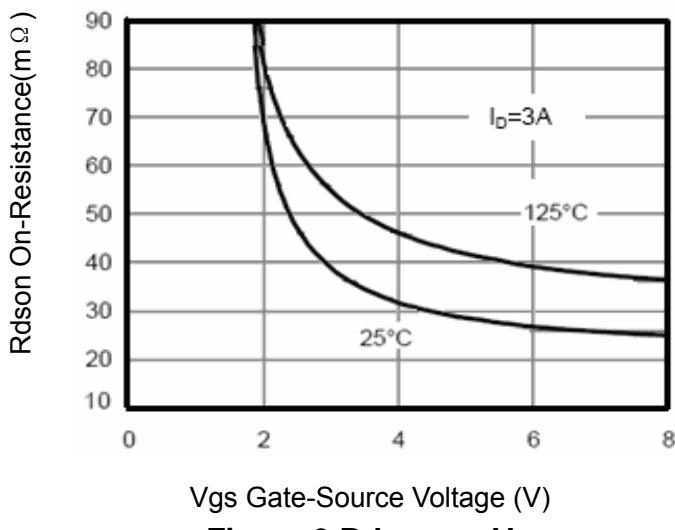
Figure 6 Drain-Source On-Resistance



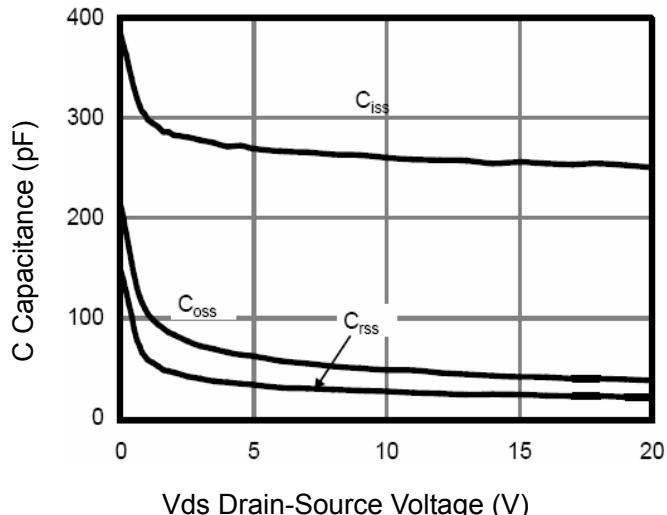
**Figure 7 Transfer Characteristics**



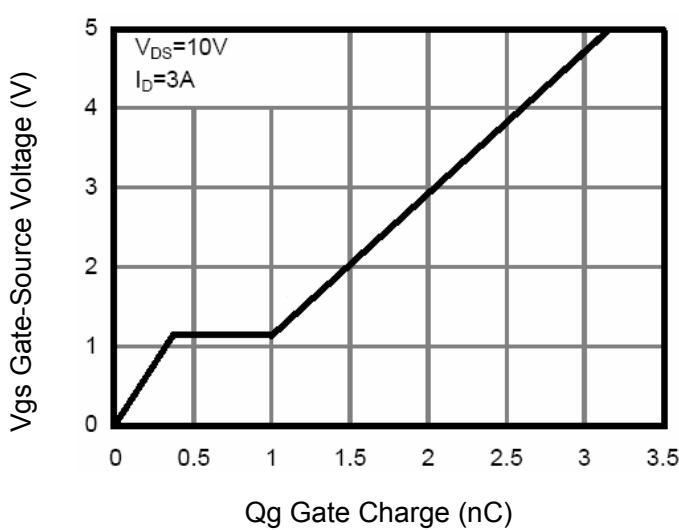
**Figure 8 Drain-Source On-Resistance**



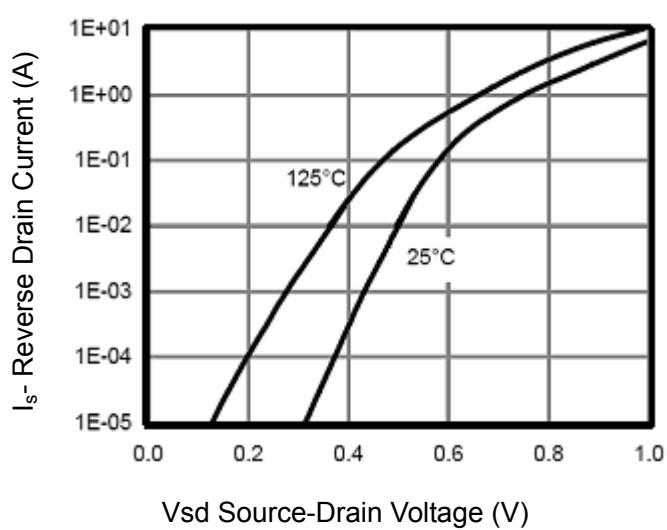
**Figure 9 Rdson vs Vgs**



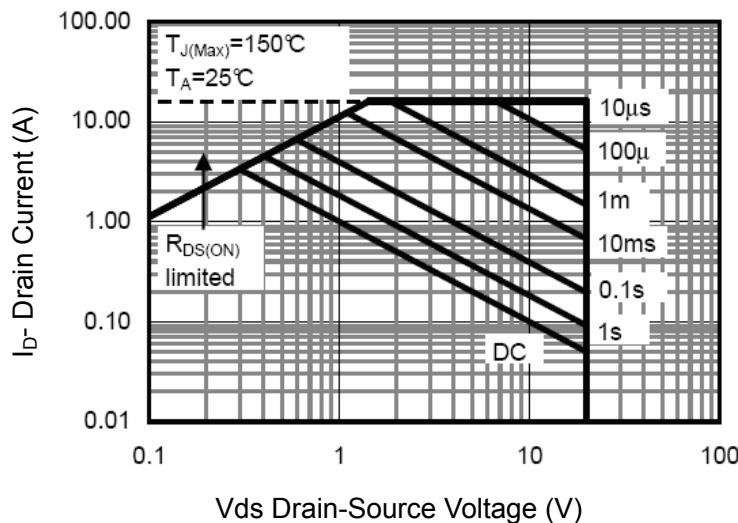
**Figure 10 Capacitance vs Vds**



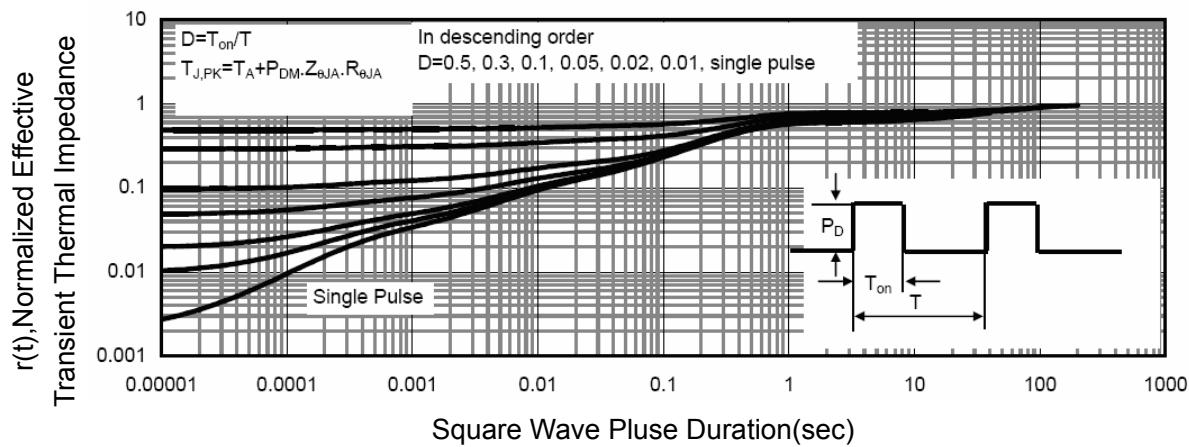
**Figure 11 Gate Charge**



**Figure 12 Source- Drain Diode Forward**



**Figure 13 Safe Operation Area**



**Figure 14 Normalized Maximum Transient Thermal Impedance**

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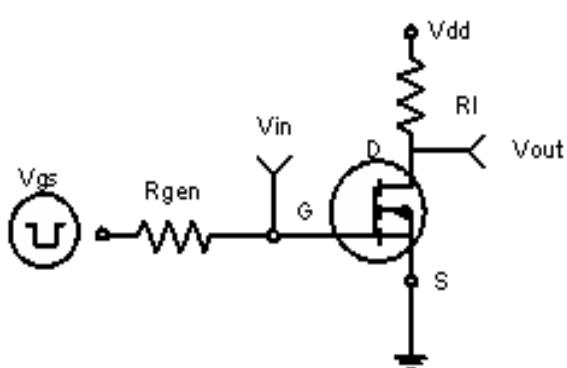


Figure 1:Switching Test Circuit

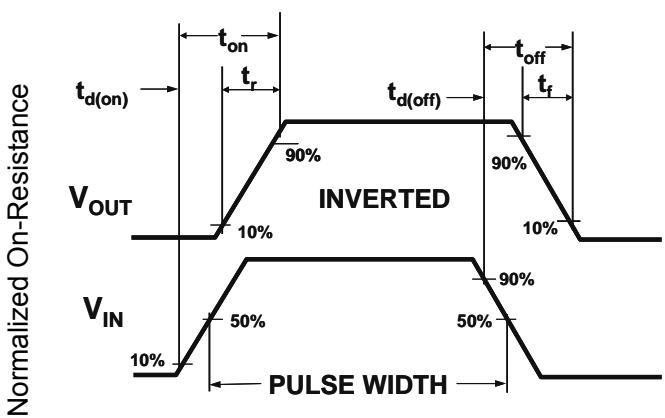


Figure 2:Switching Waveforms

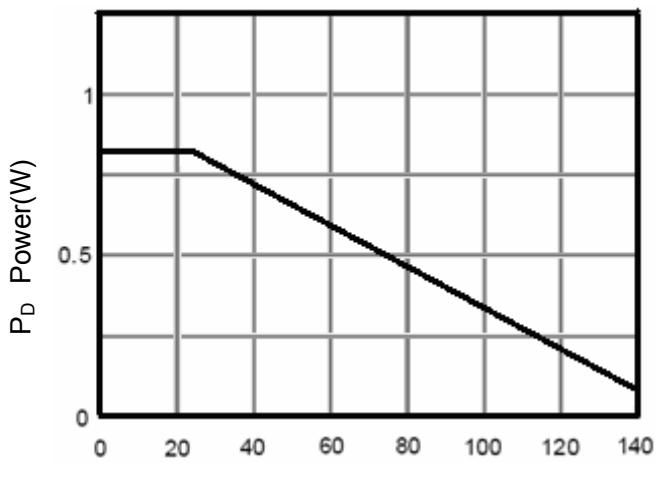


Figure 3 Power Dissipation

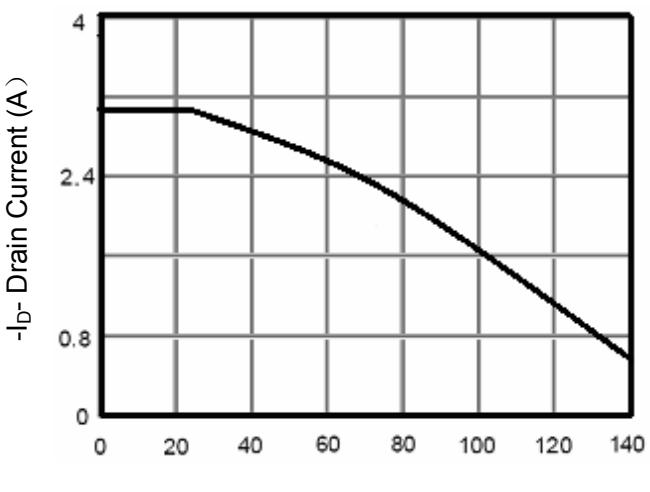


Figure 4 Drain Current

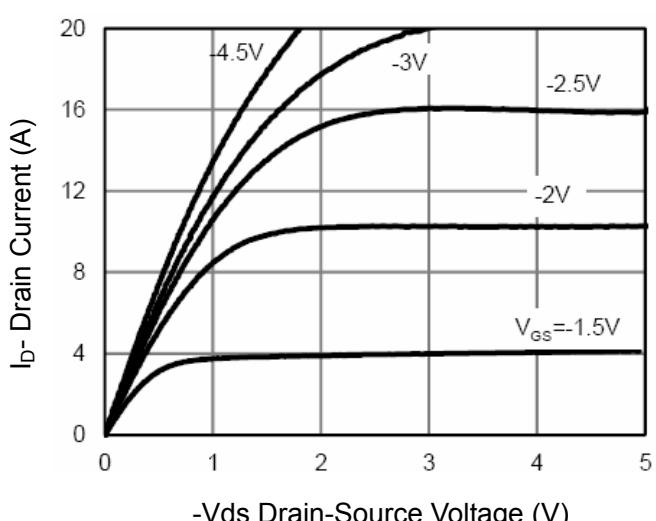


Figure 5 Output Characteristics

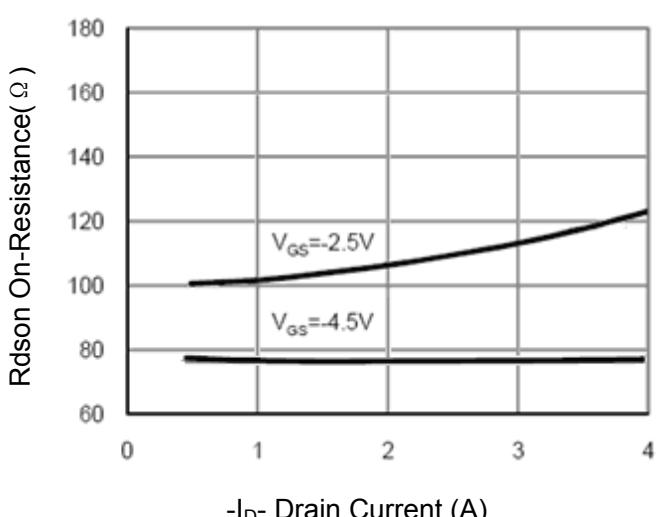
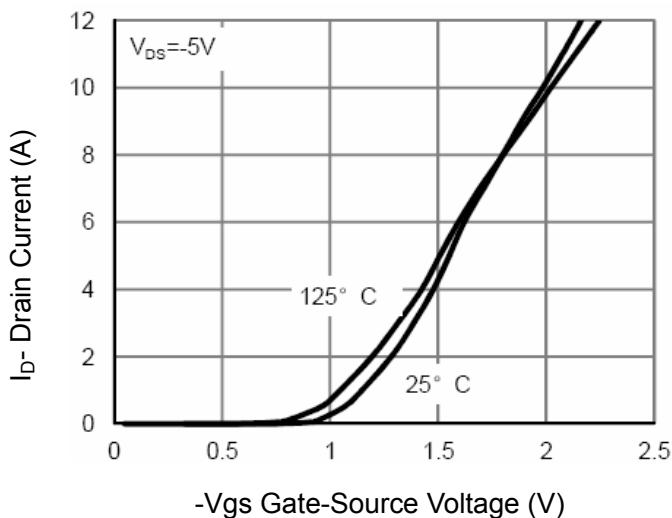
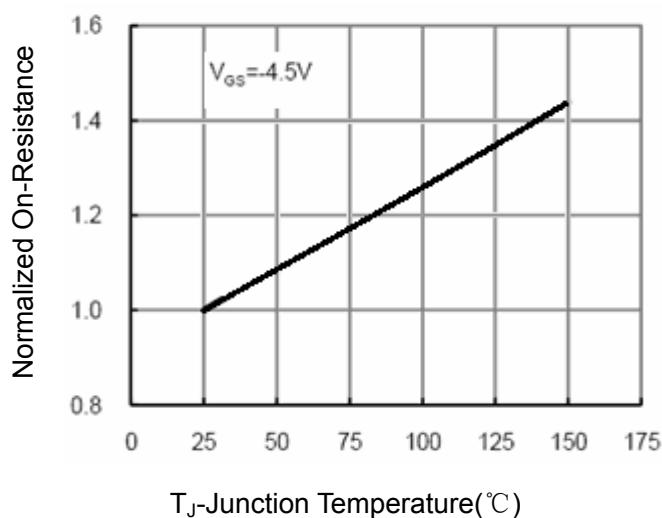


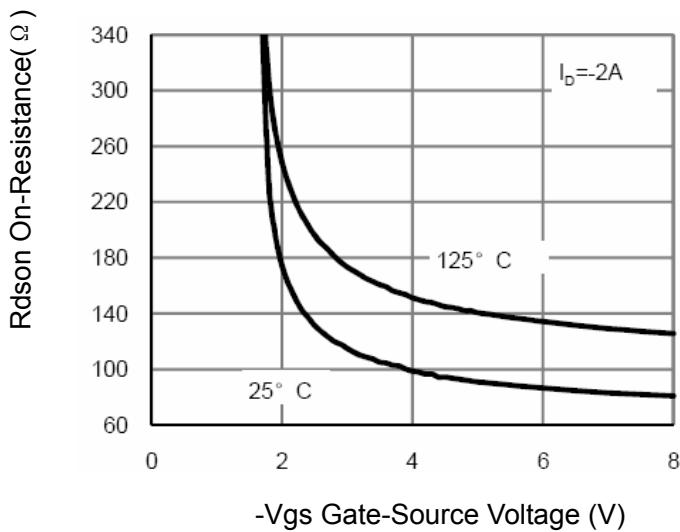
Figure 6 Drain-Source On-Resistance



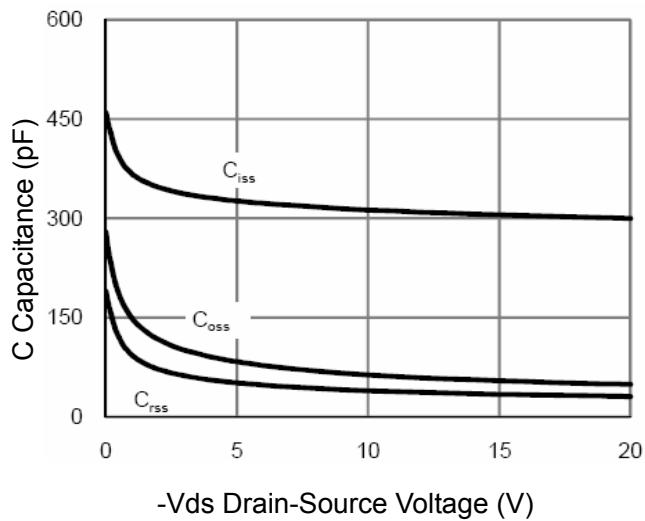
**Figure 7 Transfer Characteristics**



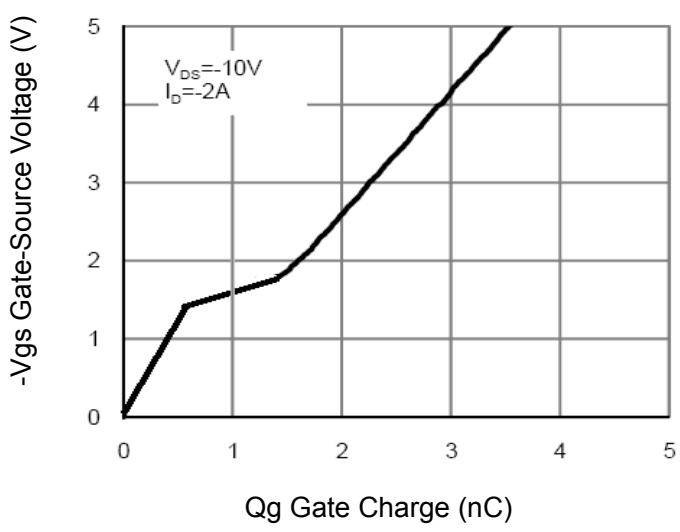
**Figure 8 Drain-Source On-Resistance**



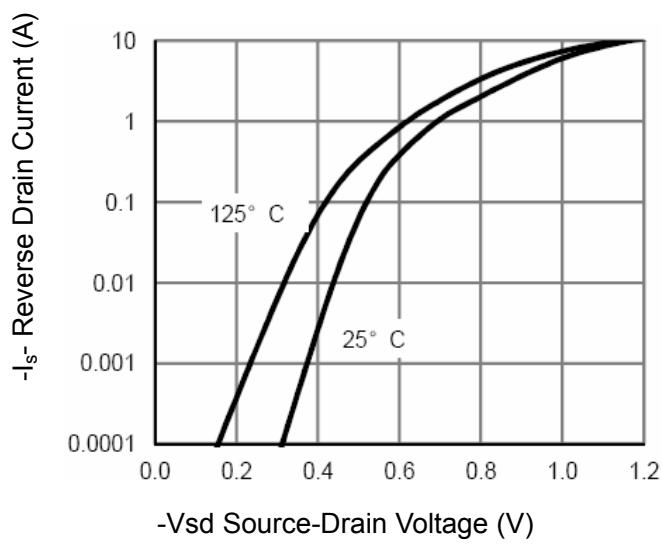
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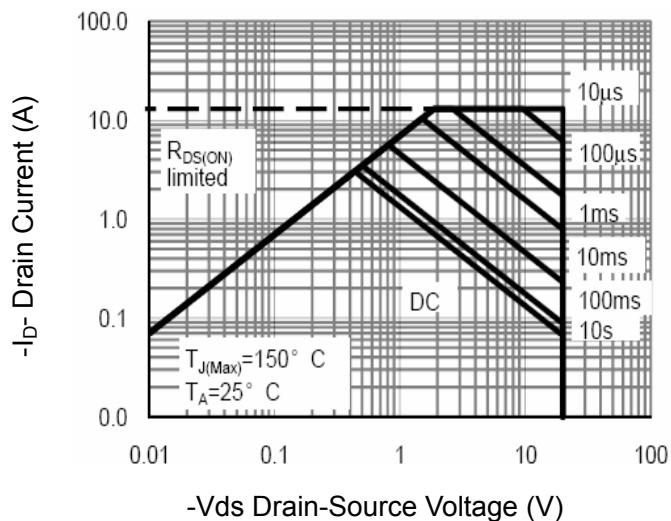
**Figure 10 Capacitance vs Vds**



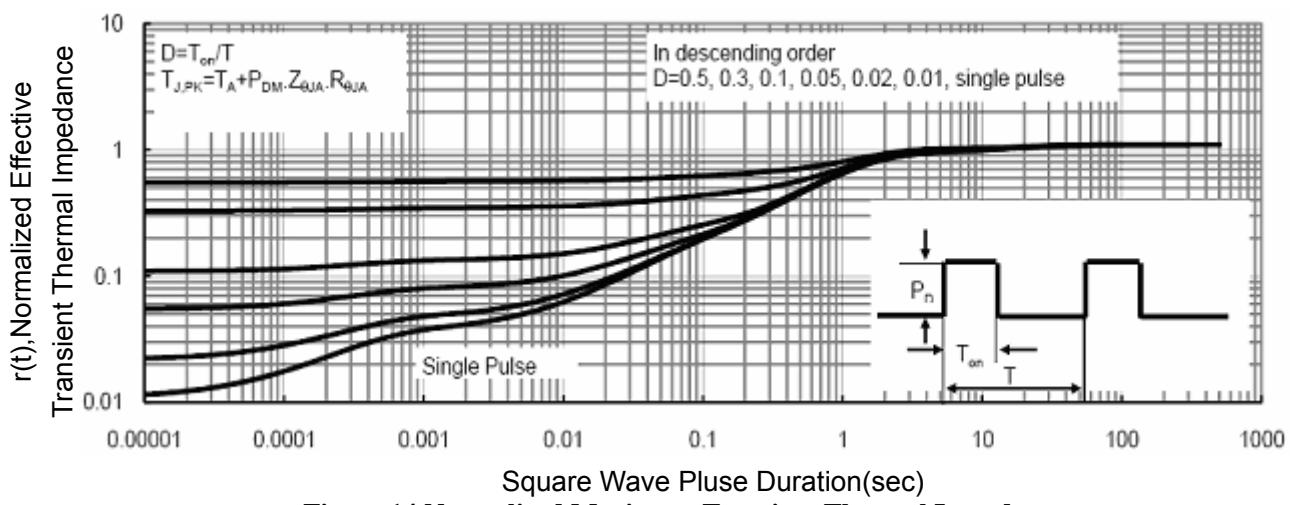
**Figure 11 Gate Charge**



**Figure 12 Source-Drain Diode Forward**

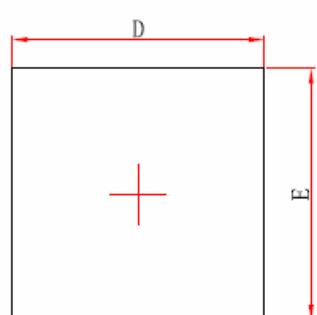


**Figure 13 Safe Operation Area**

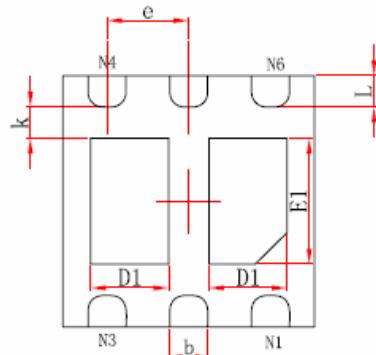


**Figure 14 Normalized Maximum Transient Thermal Impedance**

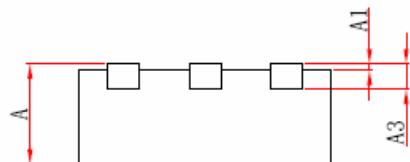
DFN2X2-6L Package Information



Top View



Bottom View



Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.520	0.720	0.020	0.028
E1	0.900	1.100	0.035	0.043
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013